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# A study of 3D Silicon pixel sensors using ROC4sens read-out chip in a DESY test beam

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A study of Silicon pixel sensors of size 50 um x 50 um fabricated at CNM using double-sided 3D technology is presented. Sensors are bump-bonded to the pixelated ROC4Sens read-out chip which exactly matches the sensor geometry. We analyze the response of two hybrid assemblies in a test beam of 5.6 GeV electrons. Results of charge collection, charge sharing, spatial resolution and efficiency are shown for non-irradiated sensors for different track incidence angles.

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